

L Number	Hits	Search Text	DB	Time stamp
-	1752	((43/460) or (438/463) or (438/606) or (438/107) or (438/620) or (438/712) or (438/718) or (438/728) or (438/733) or (738/742)).CCLS.	USPAT; US-PGPUB	2003/10/14 08:06
-	11	((43/460) or (438/463) or (438/606) or (438/107) or (438/620) or (438/712) or (438/718) or (438/728) or (438/733) or (738/742)).CCLS.) and (thinning with (substrate wafer)) and ("grid" "waffle")	USPAT; US-PGPUB	2003/07/21 09:50
-	260	(thinning with (substrate wafer)) and ("grid" "waffle")	USPAT; US-PGPUB	2003/07/22 10:09
-	11	("5096854" "5213657" "5840614" "5891298" "5968849" "5981391" "6017822" "6020252" "6033995" "6046117" "6100166").PN.	USPAT	2003/07/21 09:48
-	0	6162702.URPN.	USPAT	2003/07/21 09:49
-	2618	(thinning with (substrate wafer))	USPAT; US-PGPUB	2003/07/21 09:51
-	15144	radio with frequency with circuit	USPAT; US-PGPUB	2003/07/21 09:51
-	0	((thinning with (substrate wafer))) with (radio with frequency with circuit)	USPAT; US-PGPUB	2003/07/21 09:52
-	27	((thinning with (substrate wafer))) and (radio with frequency with circuit)	USPAT; US-PGPUB	2003/07/21 09:52
-	7	5336930.URPN.	USPAT	2003/07/21 10:02
-	13	5221221.URPN.	USPAT	2003/07/21 10:19
-	7	5336930.URPN.	USPAT	2003/07/21 10:20
-	9	("3648131" "4447291" "4507674" "4789645" "4849376" "4965218" "4970578" "4972250" "4977100").PN.	USPAT	2003/07/21 10:21
-	10	4970578.URPN.	USPAT	2003/07/21 10:22
-	10	4970578.URPN.	USPAT	2003/07/21 10:29
-	14	("3986196" "4091408" "4374394" "4376287" "4571611" "4601096" "4751562" "4794093" "4807022" "4818724" "4823174" "4827610" "4868613" "4896194").PN.	USPAT	2003/07/21 10:30
-	12	4868613.URPN.	USPAT	2003/07/21 10:32
-	12	5064772.URPN.	USPAT	2003/07/21 10:35
-	0	mmic with thining with (substrate wafer)	USPAT; US-PGPUB	2003/07/21 10:35
-	0	mmic and (thining with (substrate wafer))	USPAT; US-PGPUB	2003/07/21 10:36
-	7	(thining with (substrate wafer))	USPAT; US-PGPUB	2003/07/21 10:37
-	2618	(thinning with (substrate wafer))	USPAT; US-PGPUB	2003/07/22 10:10
-	29	((thinning with (substrate wafer))) and mmic	USPAT; US-PGPUB	2003/07/21 10:38
-	0	10034723.bn.	USPAT; US-PGPUB	2003/07/21 11:38
-	0	"10034723"	USPAT; US-PGPUB	2003/07/21 11:41
-	0	((thinning with (substrate wafer))) and vernier with marker	USPAT; US-PGPUB	2003/07/21 11:41
-	48	vernier with marker	USPAT; US-PGPUB	2003/07/21 11:48
-	438	438/462.ccls.	USPAT; US-PGPUB	2003/07/21 11:49
-	41	438/462.ccls. and thinning with (substrate wafer)	USPAT; US-PGPUB	2003/07/21 11:51
-	0	438/462.ccls. and mmisc	USPAT; US-PGPUB	2003/07/21 11:51
-	7	438/462.ccls. and mmic	USPAT; US-PGPUB	2003/07/21 11:52
-	29	438/462.ccls. and depth with mark	USPAT; US-PGPUB	2003/07/21 12:03
-	2	438/462.ccls. and backside and (depth with mark)	USPAT; US-PGPUB	2003/07/21 12:04

-	12	438/462.ccls. and backside and ((alignment depth) with mark) "09034747"	USPAT; US-PGPUB	2003/07/21 13:03
-	0	"10034747"	USPAT; US-PGPUB	2003/07/21 13:05
-	2	measured with via with etch with etching	USPAT; US-PGPUB	2003/07/21 13:05
-	0	(measured with via with hole with etching) and bernier	USPAT; US-PGPUB	2003/07/21 13:06
-	0	(measured with via with hole with etching) and vernier	USPAT; US-PGPUB	2003/07/21 13:06
-	6	measured with via with hole with etching	USPAT; US-PGPUB	2003/07/21 13:06
-	1945	hemt	USPAT; US-PGPUB	2003/07/22 08:50
-	382	hemt and mmic	USPAT; US-PGPUB	2003/07/22 08:50
-	117	(hemt and mmic) and pad	USPAT; US-PGPUB	2003/07/22 08:50
-	0	((hemt and mmic) and pad) and thinning with (substrate wafer)	USPAT; US-PGPUB	2003/07/22 08:57
-	37	((hemt and mmic) and pad) and (thin thins thinning) with (substrate wafer)	USPAT; US-PGPUB	2003/07/22 08:59
-	87	(hemt and mmic) and mmic and ((source and drain) with region)	USPAT; US-PGPUB	2003/07/22 09:01
-	21	((hemt and mmic) and mmic and ((source and drain) with region)) and ((source and drain) with pad)	USPAT; US-PGPUB	2003/07/22 09:01
-	261	(thinning with (substrate wafer)) and ("grid" "waffle")	USPAT; US-PGPUB	2003/07/22 10:10
-	2624	(thinning with (substrate wafer))	USPAT; US-PGPUB	2003/07/22 10:10
-	22264	metal with mask	USPAT; US-PGPUB	2003/07/22 10:11
-	14	((thinning with (substrate wafer))) with (metal with mask)	USPAT; US-PGPUB	2003/07/22 10:11
-	1708	uchiyama.inv.	USPAT; US-PGPUB	2003/10/06 14:12
-	1079	uchiyama.inv. and (hole via trench opening)	USPAT; US-PGPUB	2003/10/06 14:12
-	257	(uchiyama.inv. and (hole via trench opening)) and (substrate wafer)	USPAT; US-PGPUB	2003/10/06 14:14
-	43	((uchiyama.inv. and (hole via trench opening)) and (substrate wafer)) and hiroyuki.inv.	USPAT; US-PGPUB	2003/10/06 14:15
-	109	uchiyama.inv. and hiroyuki.inv.	USPAT; US-PGPUB	2003/10/06 14:20
-	188	(438/667).CCLS.	USPAT; US-PGPUB	2003/10/06 14:20
-	4	("5243498" "5434094" "5488253" "5646067").PN.	USPAT	2003/10/06 14:45
-	16	5322816.URPN.	USPAT	2003/10/06 14:56
-	4	("5243498" "5434094" "5488253" "5646067").PN.	USPAT	2003/10/06 14:58
-	0	6365513.URPN.	USPAT	2003/10/06 14:58
-	54	("5046239" "5063177" "5172050" "5229647" "5236551" "5249450" "5404044" "5420520" "5426072" "5483741" "5484647" "5487999" "5528080" "5541525" "5557844" "5578526" "5592736" "5607818" "5633122" "5634267" "5674785" "5686317" "5716218" "5781022" "5783461" "5783865" "5796590" "5801452" "5815000" "5834945" "5869974" "5876580" "5878485" "5896036" "5915977" "5929647" "5931685" "5936847" "5952840" "5962921" "6013948" "6040702" "6107109" "6107119" "6114240" "6162997" "6294837" "6353328" "6356098" "6362637" "6400172" "6417685" "6437591" "6451624").PN.	USPAT	2003/10/06 15:00
-	29	5528080.URPN.	USPAT	2003/10/06 15:04

-	15	("2770761" "3895967" "3897361" "3904442" "3979820" "4074342" "4239312" "4275410" "4370179" "4535424" "4660066" "4720308" "4761681" "4773972" "4860084").PN.	USPAT	2003/10/06 15:09
-	0	438/667.clas.	USPAT; US-PGPUB	2003/10/07 08:30
-	0	438/667.class	USPAT; US-PGPUB	2003/10/07 08:30
-	0	438/667.ccls/	USPAT; US-PGPUB	2003/10/07 08:30
-	188	438/667.ccls.	USPAT; US-PGPUB	2003/10/07 08:30
-	6	438/667.ccls. and (ecr ocp)	USPAT; US-PGPUB	2003/10/07 08:30
-	8	438/667.ccls. and (ecr icp)	USPAT; US-PGPUB	2003/10/07 08:50
-	786	((438/113) or (438/464)).CCLS.	USPAT; US-PGPUB	2003/10/07 08:51
-	0	((438/113) or (438/464)).CCLS.) and ((substrate wafer) with (segregation))	USPAT; US-PGPUB	2003/10/07 08:52
-	441	((substrate wafer) with (segregation))	USPAT; US-PGPUB	2003/10/07 08:52
-	0	((438/113) or (438/464)).CCLS.) and (((substrate wafer) with (segregation)))	USPAT; US-PGPUB	2003/10/07 08:52
-	170	((substrate wafer) with (segregation))) and ((438/\$).ccls.)	USPAT; US-PGPUB	2003/10/07 08:54
-	44	((438/113) or (438/464)).CCLS.) and (mount\$4 with front\$3)	USPAT; US-PGPUB	2003/10/07 10:01
-	563	(438/459).CCLS.	USPAT; US-PGPUB	2003/10/07 10:02
-	535	(438/460).CCLS.	USPAT; US-PGPUB	2003/10/07 10:02
-	2	((438/459).CCLS.) and mmic	USPAT; US-PGPUB	2003/10/07 10:02
-	7	((438/460).CCLS.) and mmic	USPAT; US-PGPUB	2003/10/07 10:04
-	0	((438/460).CCLS.) and mmic) and (ecr icp)	USPAT; US-PGPUB	2003/10/07 10:04
-	188	(438/667).CCLS.	USPAT; US-PGPUB	2003/10/14 08:06
-	50	((438/667).CCLS.) and (metal with mask\$3)	USPAT; US-PGPUB	2003/10/14 08:07